

SN74LV157A Quadruple 2-Line to 1-Line Data Selectors/Multiplexers

1 Features

- Operates 2 V to 5.5 V V_{CC}
- Inputs accept voltages to 5.5 V
- Max t_{pd} of 7.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} , $T_A = 25^\circ C$
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at V_{CC} , $T_A = 25^\circ C$
- Latch-up performance exceeds 100 mA per JESD 78, Class II

2 Applications

- Servers
- LED Displays
- Network Switches
- Telecom Infrastructure
- Motor Drivers
- I/O Expanders

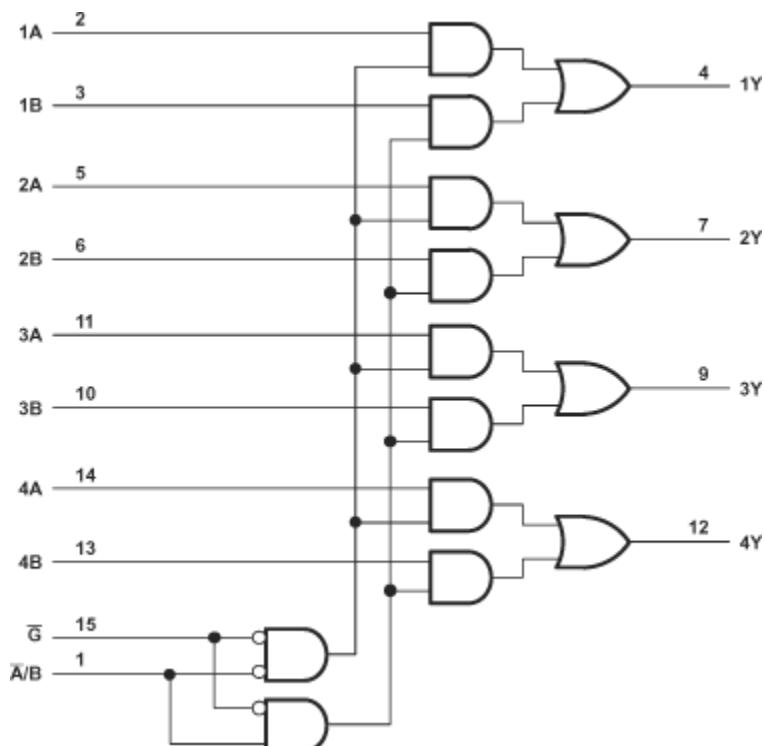
3 Description

The 'LV157A devices are quadruple 2-line to 1-line data selectors/multiplexers designed for 2 V to 5.5 V V_{CC} operation.

Package Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74LV157A	DB (SSOP, 16)	6.2 mm × 5.3 mm
	DGV (TSSOP, 16)	3.6 mm × 4.4 mm
	DW (SOIC,16)	10.3 mm × 7.5 mm
	NS (SOP, 16)	10.3 mm × 5.3 mm
	PW (TSSOP, 16)	5 mm × 4.4 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Logic Diagram (Positive Logic)

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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision F (April 1998) to Revision G (March 2023)	Page
• Added <i>Applications</i> , <i>Package Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....	1

5 Pin Configuration and Functions

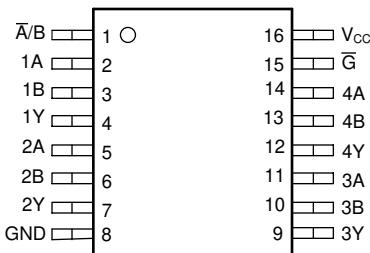


Figure 5-1. D, DB, DGV, NS, or PW Package (Top View)

Table 5-1. Pin Functions

PIN		I/O ⁽¹⁾	DESCRIPTION
NO.	NAME		
1	A/B	I	Address select
2	1A	I	Channel 1, data input A
3	1B	I	Channel 1, data input B
4	1Y	I	Channel 1, data output
5	2A	O	Channel 2, data input A
6	2B	O	Channel 2, data input B
7	2Y	I	Channel 2, data output
8	GND	—	Ground
9	3Y	I	Channel 3, data output
10	3B	I	Channel 3, data input B
11	3A	I	Channel 3, data input A
12	4Y	I	Channel 4, data output
13	4B	I	Channel 4, data input B
14	4A	I	Channel 4, data input A
15	G	I	Output strobe, active low
16	V _{cc}	—	Positive supply

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	-0.5	7	V
V_I	Input voltage ¹	-0.5	7	V
V_O	Output voltage range applied in high or low state ^{1 (1)}	-0.5	$V_{CC} + 0.5$	V
V_O	Output voltage range applied in power-off state ¹	-0.5	7	V
I_{IK}	Input clamp current	$V_I < 0$	-20	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}	± 25	mA
	Continuous current through V_{CC} or GND		± 50	mA
T_{stg}	Storage temperature	-65	150	°C

(1) This value is limited to 5.5 V maximum.

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device.

These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Human-Body Model (A114-A) ⁽¹⁾	± 2000	V
	Machine Model (A115-A)	± 200	
	Charged-Device Model (C101) ⁽²⁾	± 1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 2\text{ V}$	1.5		V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	$V_{CC} \times 0.7$		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	$V_{CC} \times 0.7$		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$V_{CC} \times 0.7$		
V_{IL}	Low-level input voltage	$V_{CC} = 2\text{ V}$	0.5		V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	$V_{CC} \times 0.3$		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	$V_{CC} \times 0.3$		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$V_{CC} \times 0.3$		
V_I	Input voltage		0	5.5	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2\text{ V}$	-50		μA
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-2		mA
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	6		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-12		
I_{OL}	Low-level output current	$V_{CC} = 2\text{ V}$	50		μA
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	2		mA
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	6		
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	12		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0	200	ns/V
		$V_{CC} = 3\text{ V to }3.6\text{ V}$	0	100	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	0	20	
T_A	Operating free-air temperature		-40	85	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74LV157A					UNIT
		D	DB	DGV	NS	PW	
		16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	73	82	120	64	108	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
V_{OH}	$I_{OH} = -50\text{ }\mu\text{A}$	2 V to 5.5 V	$V_{CC} - 0.1$			V
	$I_{OH} = -2\text{ mA}$	2.3 V	2			
	$I_{OH} = -6\text{ mA}$	3 V	2.48			
	$I_{OH} = -12\text{ mA}$	4.5 V	3.8			

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{OL}	I _{OL} = 50 μ A	2 V to 5.5 V			0.1	V
	I _{OL} = 2 mA	2.3 V			0.4	
	I _{OL} = 6 mA	3 V			0.44	
	I _{OL} = 12 mA	4.5 V			0.55	
I _I	V _I = 5.5 V or GND	0 to 5.5 V			\pm 1	μ A
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			20	μ A
I _{off}	V _I or V _O = 0 to 5.5 V	0			5	μ A
C _i	V _I = V _{CC} or GND	3.3 V		1.7		pF

6.6 Switching Characteristics, V_{CC} = 2.5 V \pm 0.2 V

over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	TA = 25°C			UNIT
				MIN	TYP	MAX	
t _{pd}	A or B	Y	C ^L = 15 pF	7.4 ¹	15.9 ¹	1	19.5
	\bar{A}/B	Y		7.9 ¹	19.4 ¹	1	23.5
	\bar{G}	Y		7.8 ¹	19.8 ¹	1	24
t _{pd}	A or B	Y	C _L = 50 pF	9.4	18.8	1	22
	\bar{A}	Y		10.8	22.3	1	26
	\bar{G}	Y		9.6	22.7	1	26.5

1. On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.7 Switching Characteristics, V_{CC} = 3.3 V \pm 0.3 V

over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	TA = 25°C			UNIT
				MIN	TYP	MAX	
t _{pd}	A or B	Y	C ^L = 15 pF	5.2 ¹	9.7 ¹	1	11.5
	\bar{A}/B	Y		5.8 ¹	13.2 ¹	1	15.5
	\bar{G}	Y		5.5 ¹	13.6 ¹	1	16
t _{pd}	A or B	Y	C _L = 50 pF	6.7	13.2	1	15
	\bar{A}	Y		7.6	16.7	1	19
	\bar{G}	Y		7	17.1	1	19.5

1. On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.8 Switching Characteristics, V_{CC} = 5 V \pm 0.5 V

over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	TA = 25°C			UNIT
				MIN	TYP	MAX	
t _{pd}	A or B	Y	C ^L = 15 pF	3.6 ¹	6.4 ¹	1	7.5
	\bar{A}/B	Y		4.1 ¹	8.1 ¹	1	9.5
	\bar{G}	Y		3.8 ¹	8.6 ¹	1	10

over recommended operating free-air temperature range, $V_{CC} = 5 V \pm 0.5 V$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	TA = 25°C			SN74LV157A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Y	$C_L = 50 \text{ pF}$		4.8	8.4	1	9.5	ns
	\bar{A}	Y			5.4	10.1	1	11.5	
	\bar{G}	Y			5	10.6	1	12	

1. On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.9 Noise Characteristics

$V_{CC} = 3.3 V$, $C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$ ⁽¹⁾

PARAMETER		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.3	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		-0.1	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3.2		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

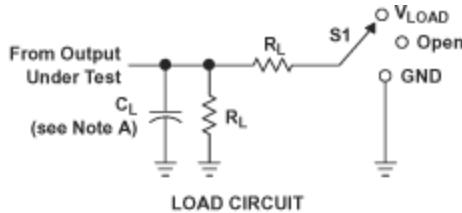
(1) Characteristics are for surface-mount packages only.

6.10 Operating Characteristics

$T_A = 25^\circ\text{C}$

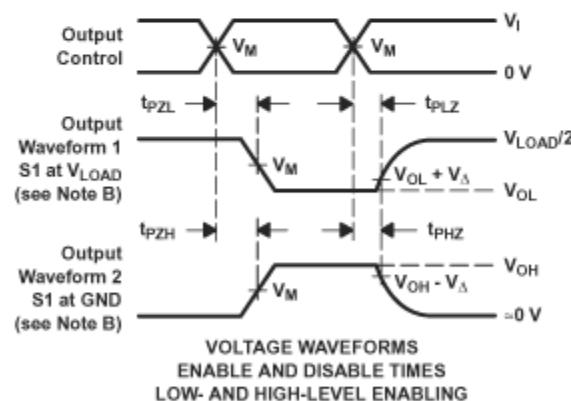
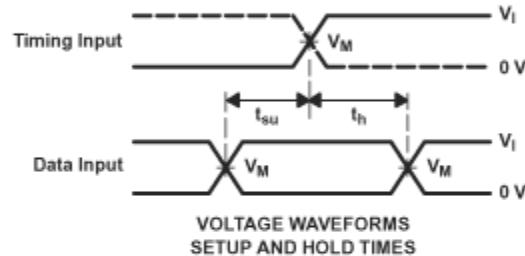
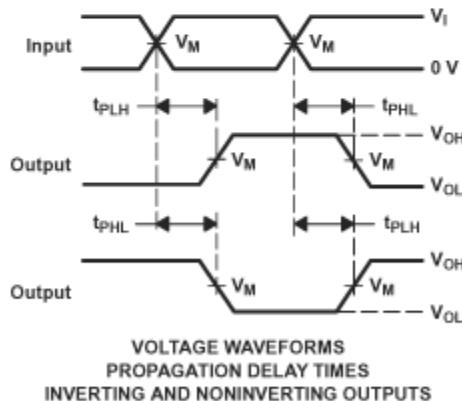
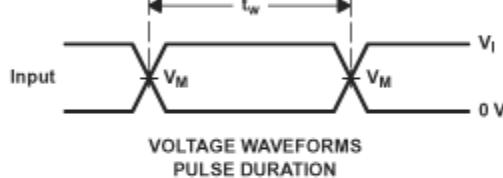
PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50 \text{ pF}$ $f = 10 \text{ MHz}$	3.3 V 5 V	12.1 13.1	pF

7 Parameter Measurement Information



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

V _{CC}	INPUTS		V _M	V _{LOAD}	C _L	R _L	V _Δ
	V _I	t _f /t _f					
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V ± 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
 D. The outputs are measured one at a time, with one transition per measurement.
 E. t_{PZL} and t_{PHZ} are the same as t_{ds}.
 F. t_{PZL} and t_{PZH} are the same as t_{on}.
 G. t_{PLH} and t_{PHL} are the same as t_{pd}.
 H. All parameters and waveforms are not applicable to all devices.

8 Detailed Description

8.1 Overview

The 'LV157A devices contain inverters and drivers to supply full data selection to the four output gates. A separate strobe (\bar{G}) input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The 'LV157A devices present true data.

8.2 Functional Block Diagram

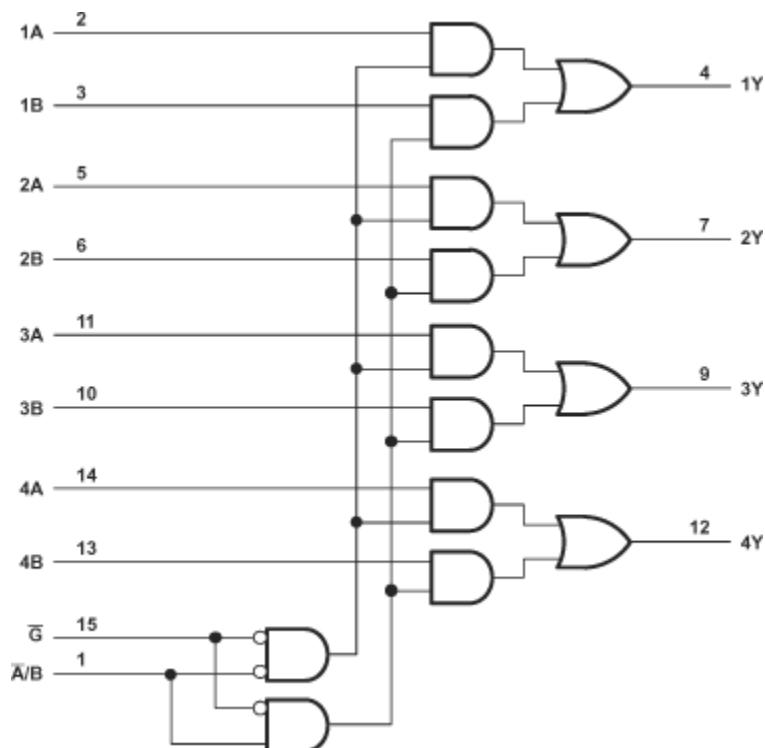


Figure 8-1. Logic Diagram (Positive Logic)

8.3 Device Functional Modes

Table 8-1. Function Table

INPUTS ⁽¹⁾		DATA		OUTPUT Y
\bar{G}	SELECT A/B	A	B	
H	X	X	X	L
L	L	L	X	L
L	L	H	X	H
L	H	X	L	L
L	H	X	H	H

(1) H = High Voltage Level, L = Low Voltage Level, X = Do not Care, Z = High Impedance

9 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

9.1 Power Supply Recommendations

The power supply can be any voltage between the min and max supply voltage rating located in [Section 6.3](#).

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1 μF capacitor is recommended. If there are multiple V_{CC} terminals then 0.01 μF or 0.022 μF capacitors are recommended for each power terminal. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. 0.1 μF and 1.0 μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for the best results.

9.2 Layout

9.2.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

9.2.1.1 Layout Example

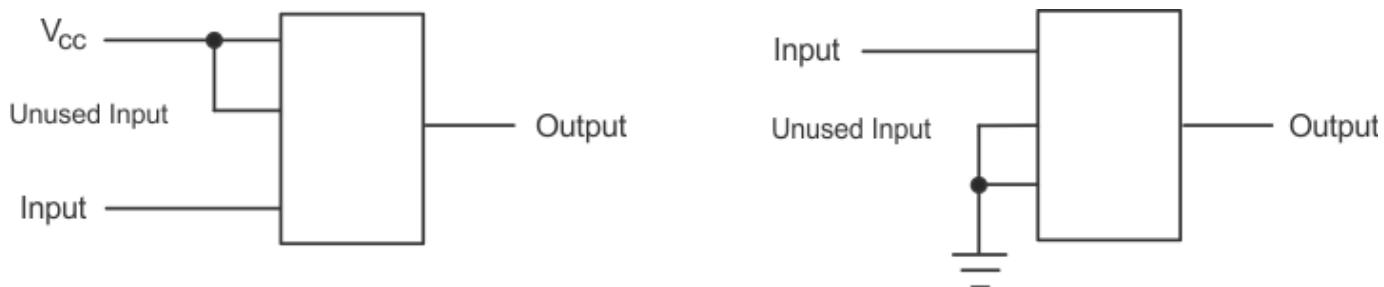


Figure 9-1. Layout Diagram

10 Device and Documentation Support

10.1 Documentation Support

10.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 10-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74LV157A	Click here				

10.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

10.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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10.4 Electrostatic Discharge Caution

 This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LV157AD	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	LV157A
SN74LV157ADBR	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A
SN74LV157ADBR.A	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A
SN74LV157ADGVR	Active	Production	TVSOP (DGV) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A
SN74LV157ADGVR.A	Active	Production	TVSOP (DGV) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A
SN74LV157ADR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A
SN74LV157ADR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A
SN74LV157ANSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV157A
SN74LV157ANSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV157A
SN74LV157APW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	LV157A
SN74LV157APWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	LV157A
SN74LV157APWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A
SN74LV157APWRG4	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

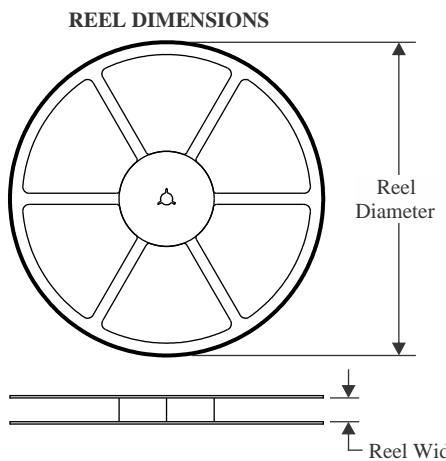
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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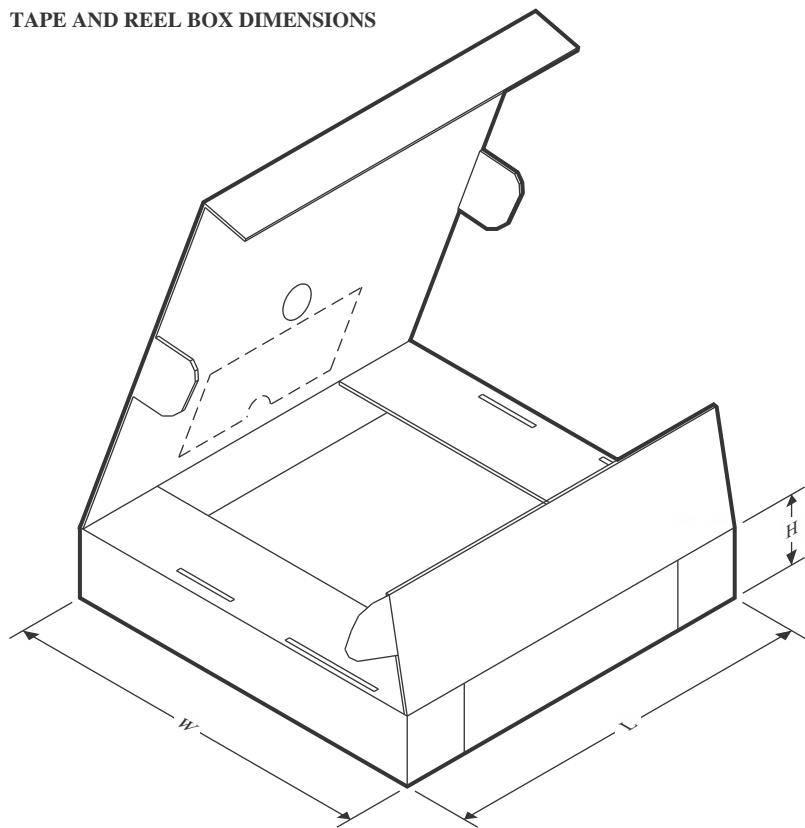
TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV157ADBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV157ADGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV157ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV157ANSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LV157APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV157APWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

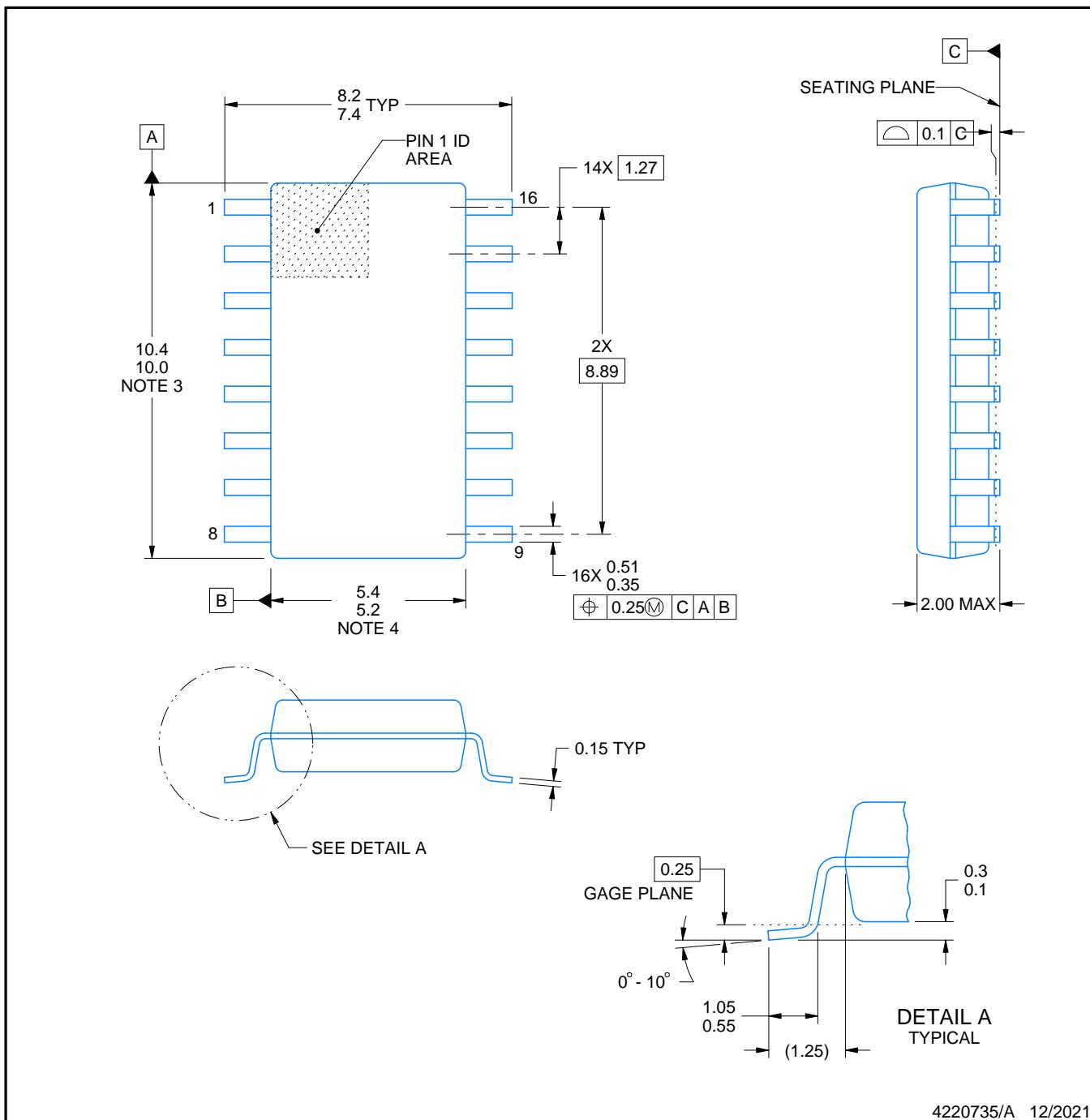
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV157ADBR	SSOP	DB	16	2000	353.0	353.0	32.0
SN74LV157ADGVR	TVSOP	DGV	16	2000	353.0	353.0	32.0
SN74LV157ADR	SOIC	D	16	2500	353.0	353.0	32.0
SN74LV157ANSR	SOP	NS	16	2000	353.0	353.0	32.0
SN74LV157APWR	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74LV157APWRG4	TSSOP	PW	16	2000	356.0	356.0	35.0



PACKAGE OUTLINE

SOP - 2.00 mm max height

SOP



NOTES:

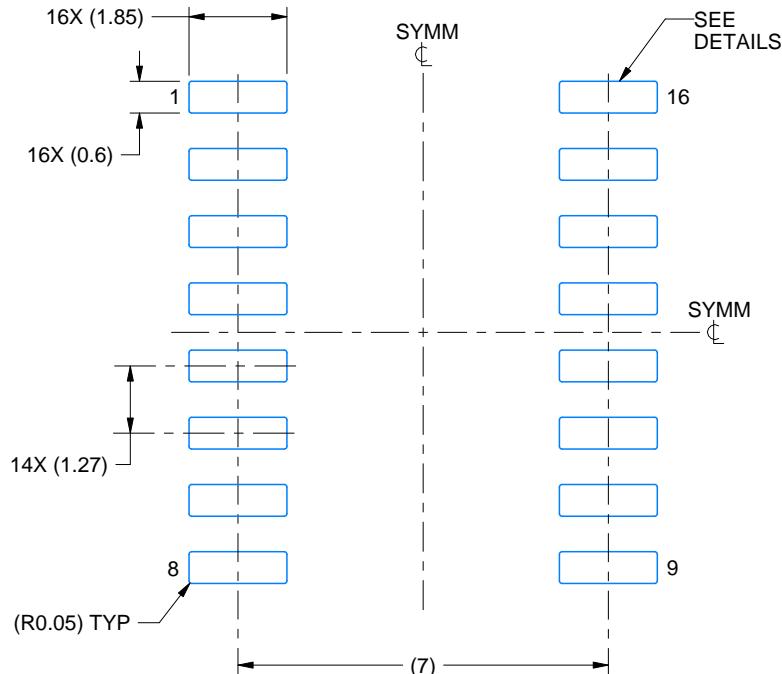
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

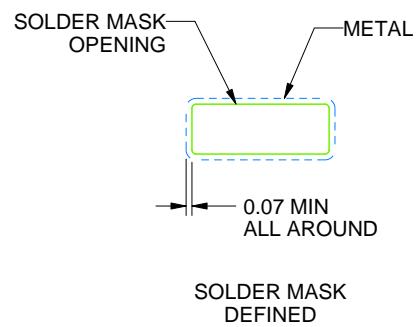
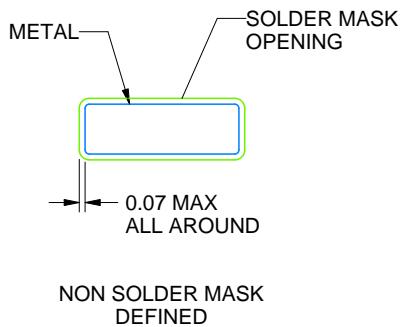
NS0016A

SOP - 2.00 mm max height

SOP



LAND PATTERN EXAMPLE
SCALE:7X



SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

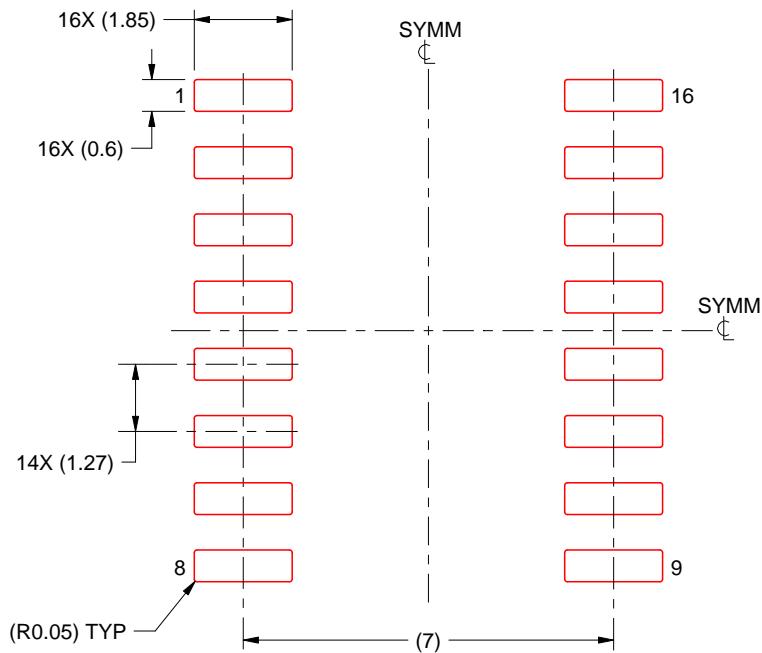
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

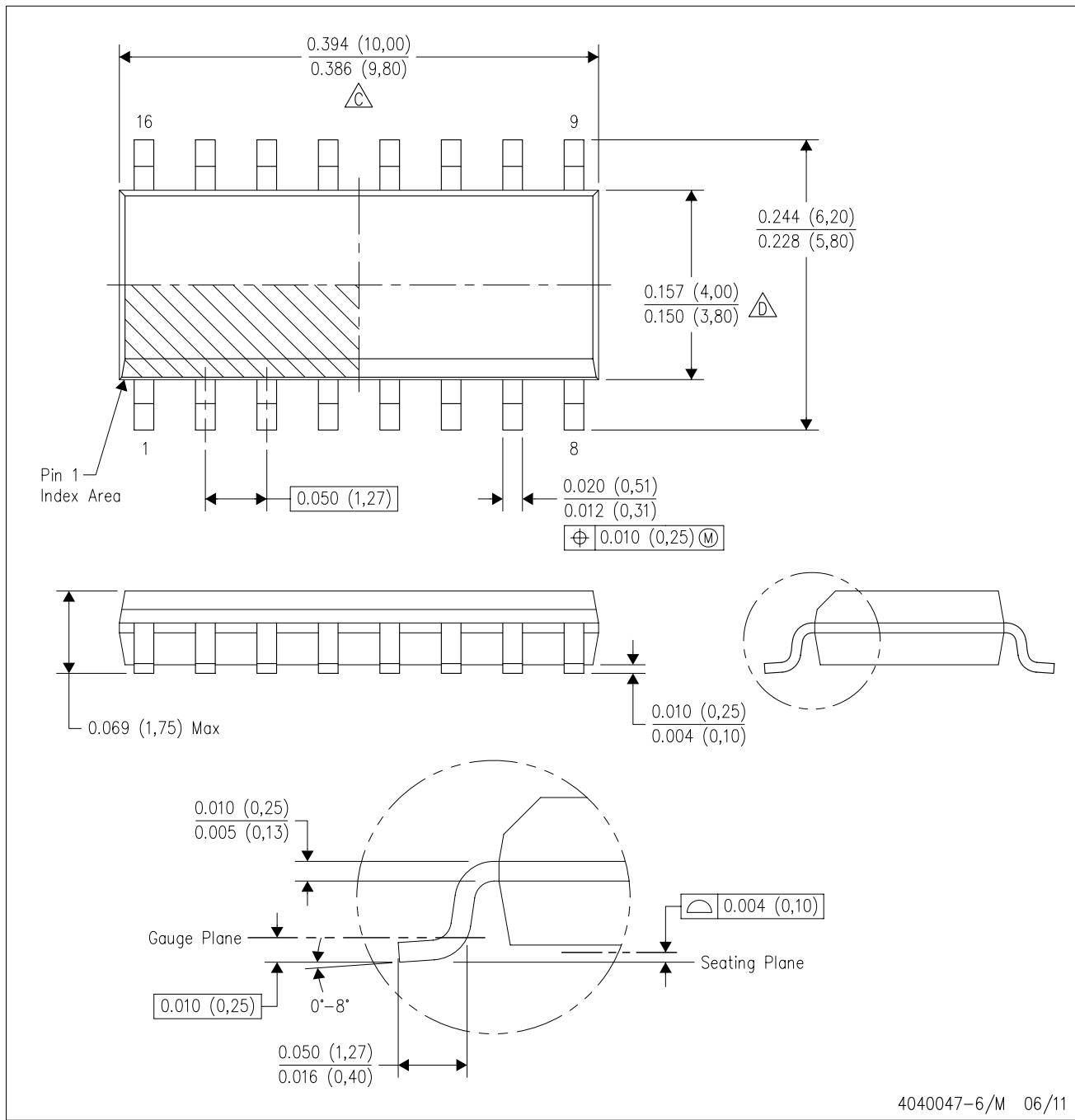
4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

E. Reference JEDEC MS-012 variation AC.

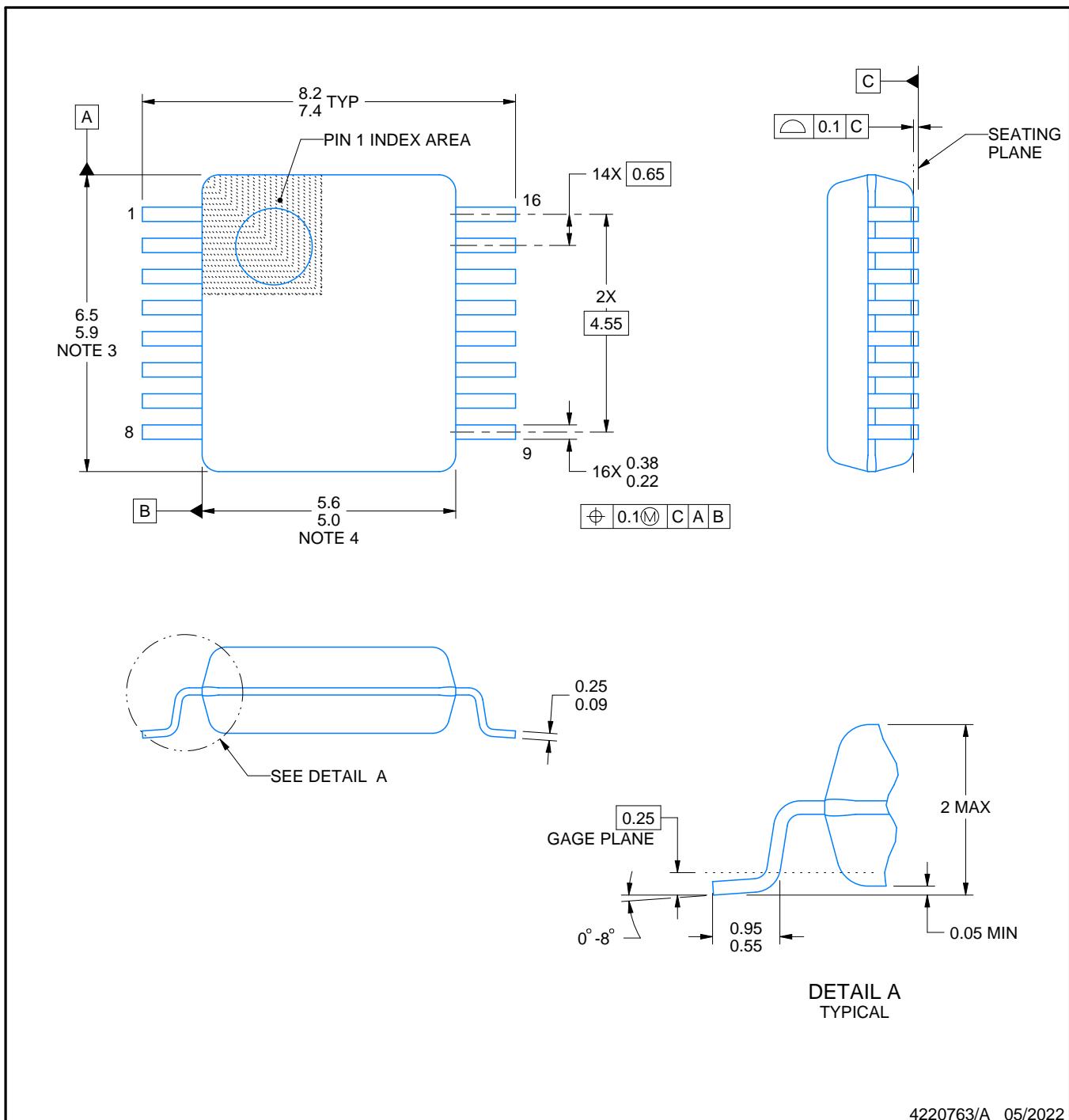
PACKAGE OUTLINE

DB0016A



SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

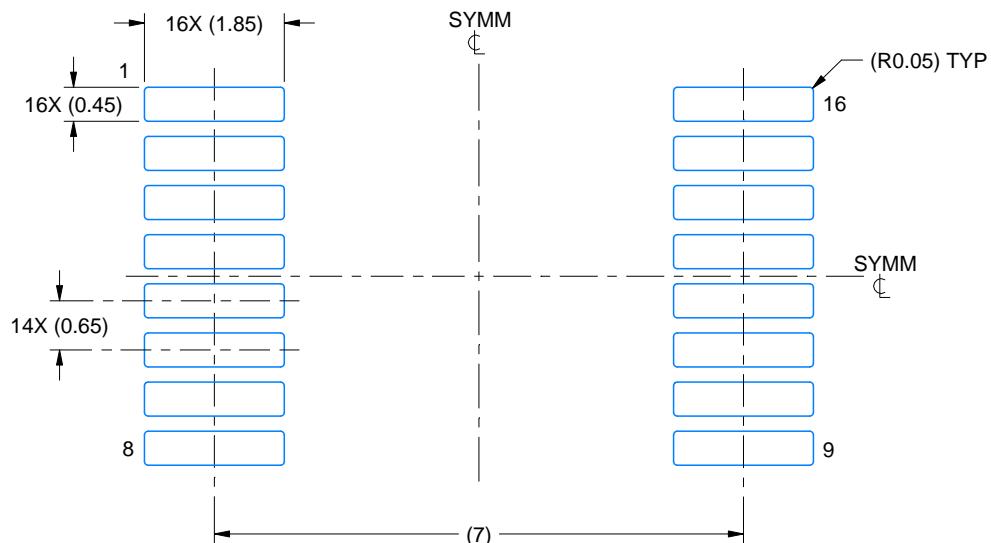
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

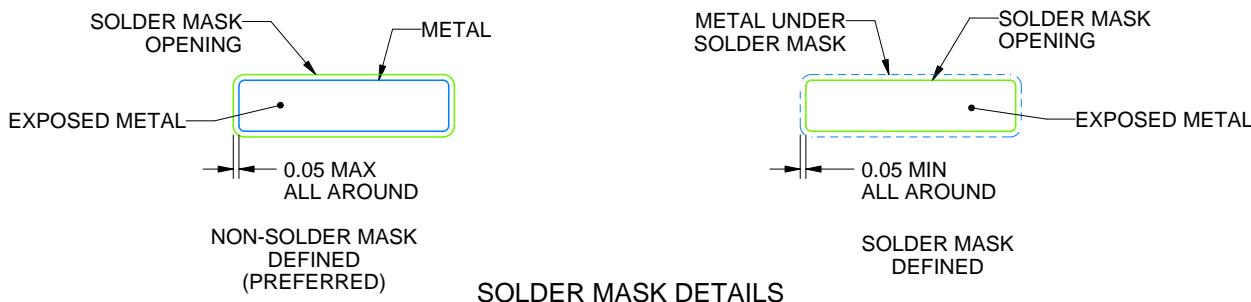
DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220763/A 05/2022

NOTES: (continued)

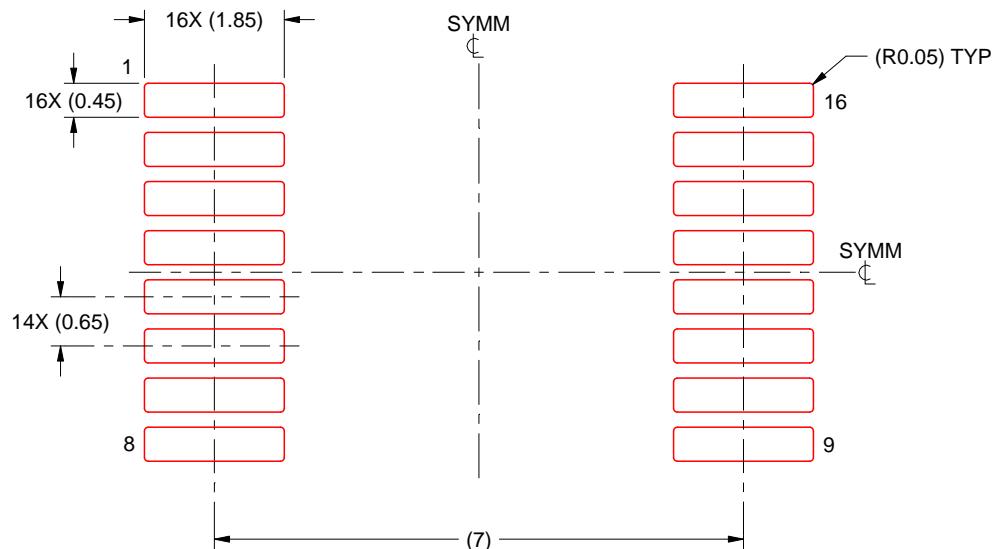
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

NOTES: (continued)

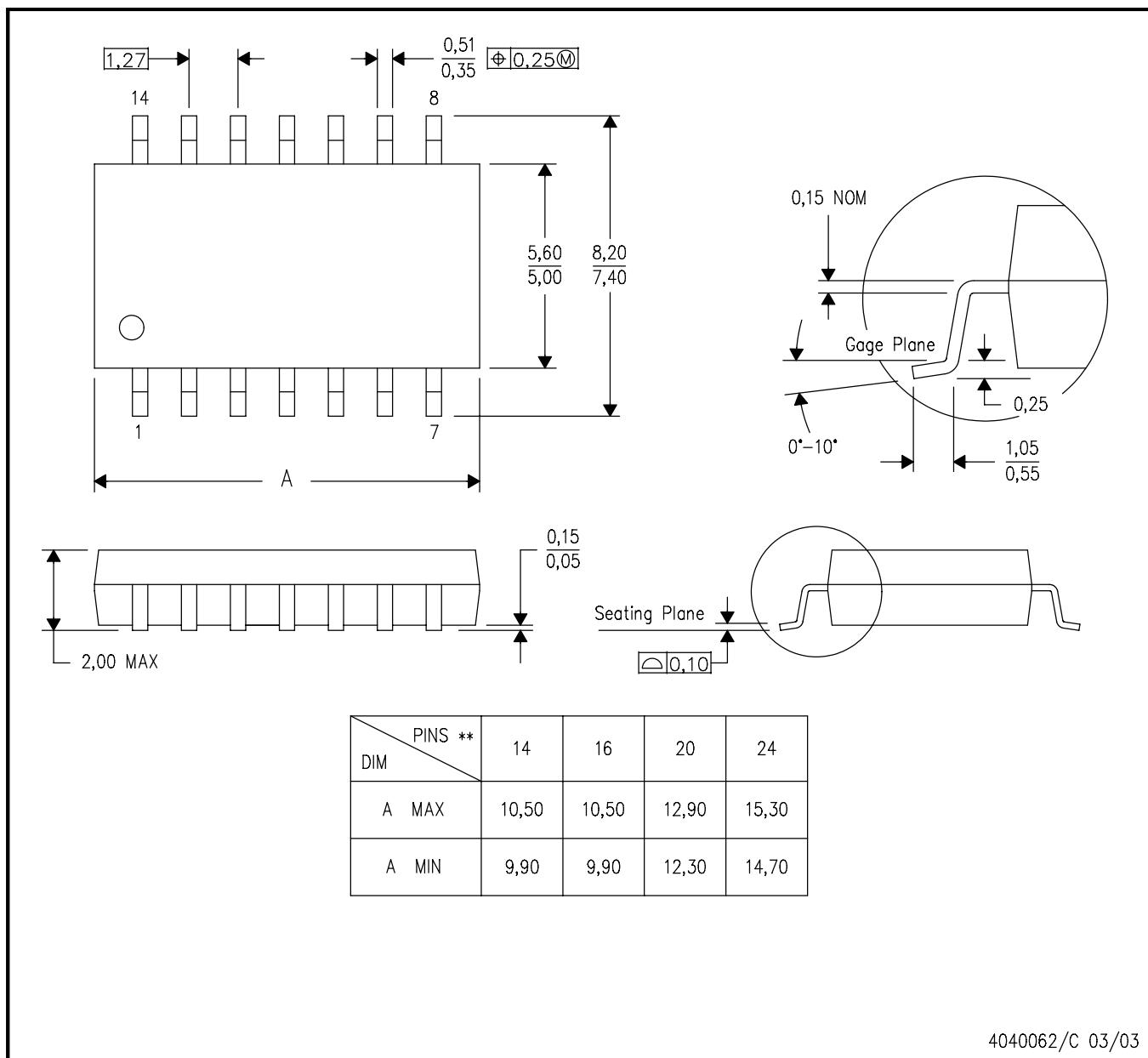
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



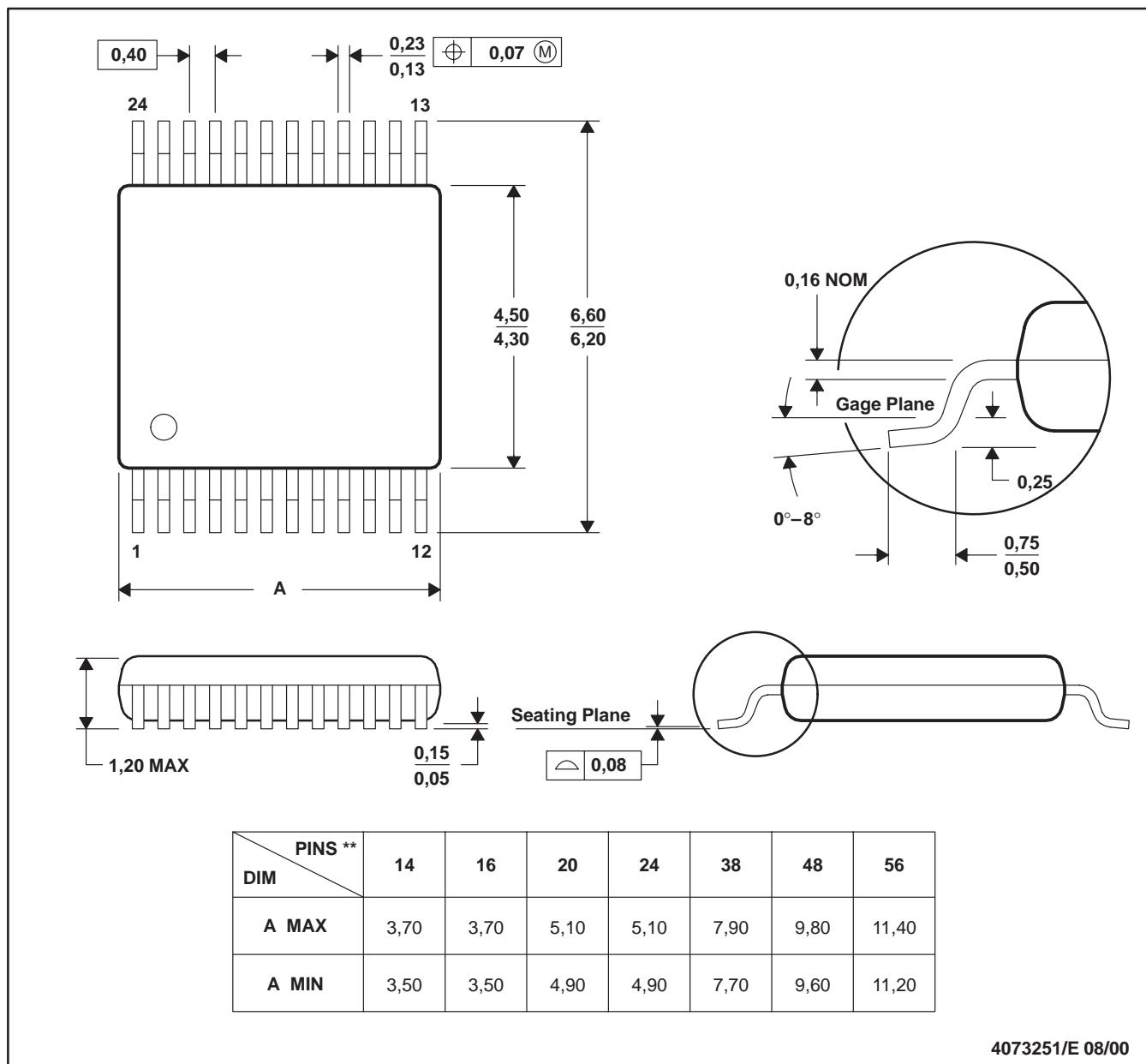
4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

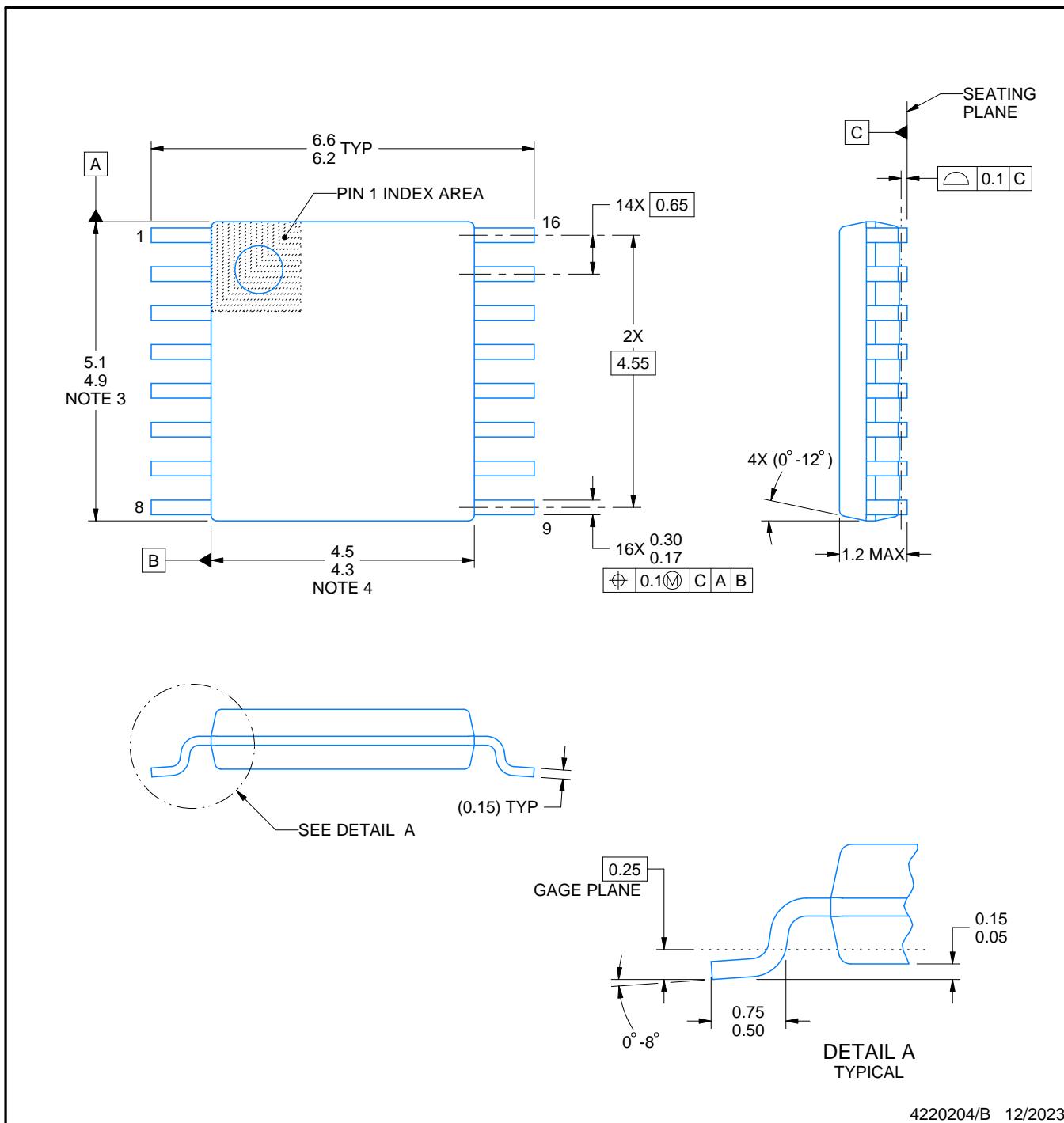
PACKAGE OUTLINE

PW0016A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

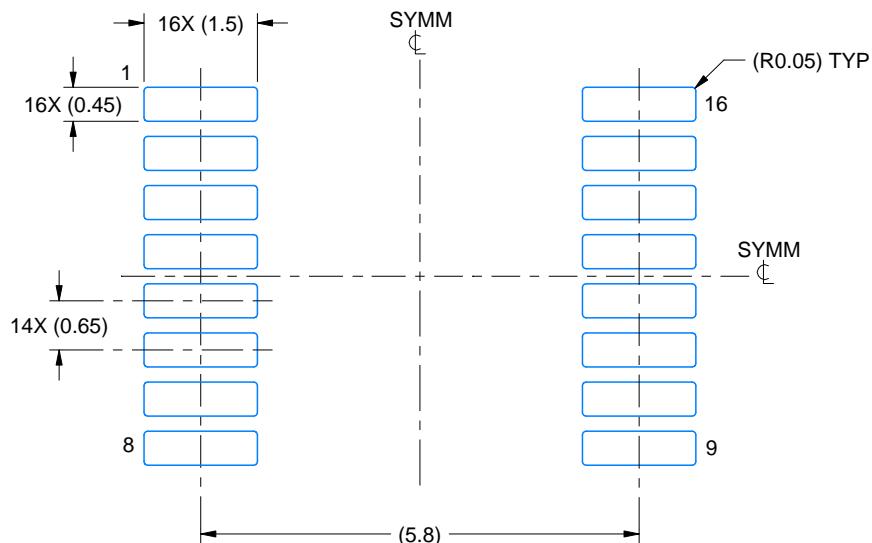
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

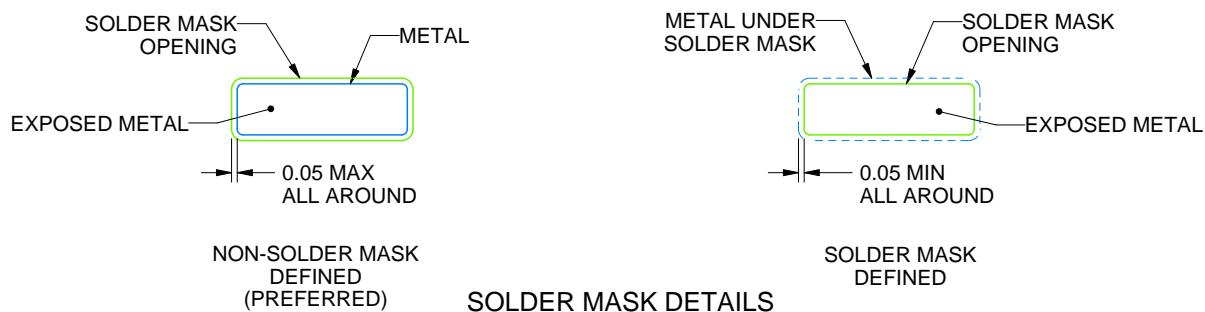
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/B 12/2023

NOTES: (continued)

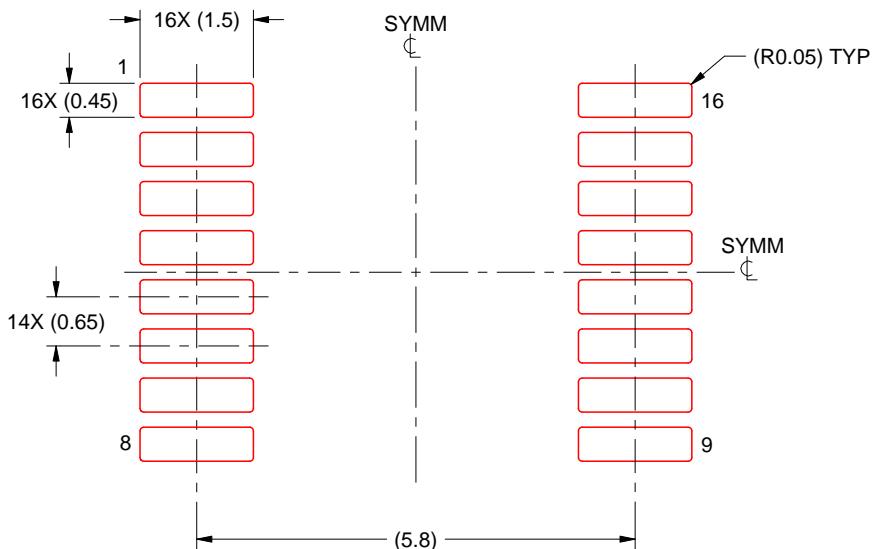
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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